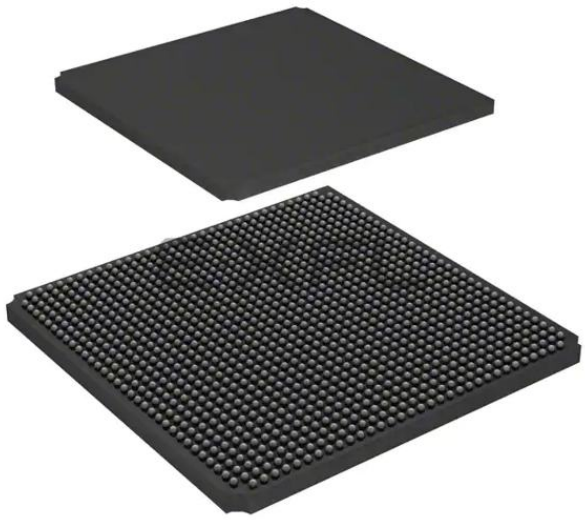
Lattice Semiconductor Corporation - LFSC3GA80E-5FF1152I Datasheet



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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

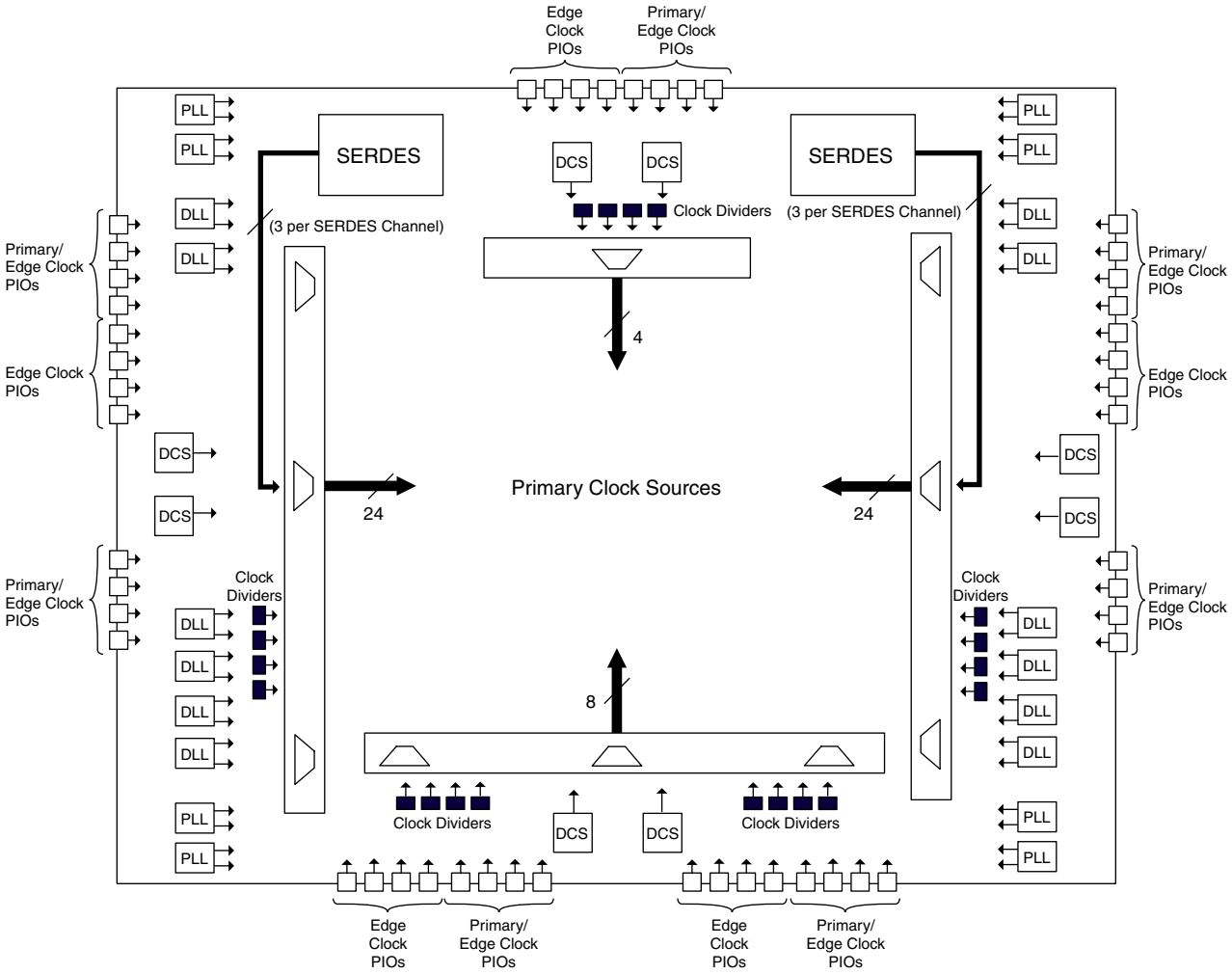
The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Obsolete
Number of LABs/CLBs	20000
Number of Logic Elements/Cells	80000
Total RAM Bits	5816320
Number of I/O	660
Number of Gates	-
Voltage - Supply	0.95V ~ 1.26V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 105°C (TJ)
Package / Case	1152-BBGA, FCBGA
Supplier Device Package	1152-FCBGA (35x35)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lfsc3ga80e-5ff1152i

- Two outputs per PLL
- Clock divider outputs
- Digital Clock Select (DCS) block outputs
- Three outputs per SERDES quad

Figure 2-5 shows the arrangement of the primary clock sources.

Figure 2-5. Clock Sources



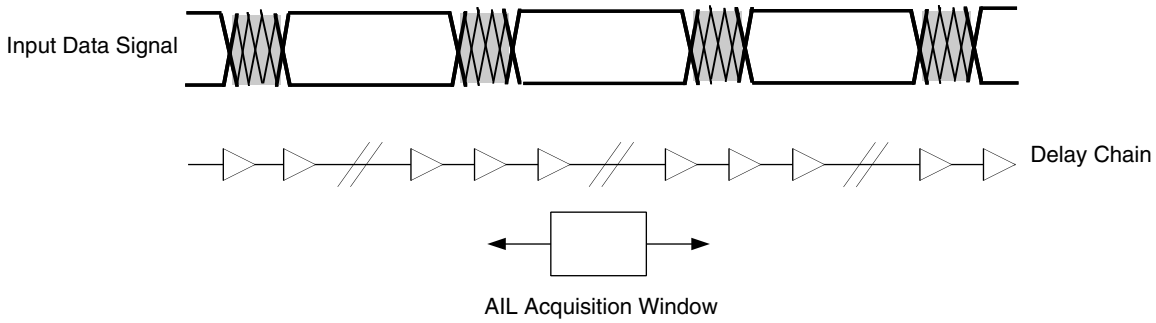
Primary Clock Routing

The clock routing structure in LatticeSC devices consists of 12 Primary Clock lines per quadrant. The primary clocks are generated from 64:1 MUXs located in each quadrant. Three of the inputs to each 64:1 MUX comes from local routing, one is connected to GND and rest of the 60 inputs are from the primary clock sources. Figure 2-6 shows this clock routing.

Adaptive Input Logic (AIL) Overview

The Adaptive Input Logic (AIL) provides the ability of the input logic to dynamically find a solution by monitoring multiple samples of the input data. The input data signal from the input buffer is run through a delay chain. Data, transitions, jitter, noise are all contained inside of the delay chain. The AIL will then search the delay chain for a clean sampling point for data. Once found the AIL will monitor and walk with the data dynamically. This novel approach of using a delay chain to create multiple copies of the data provides a lower power solution than oversampling data with a higher speed clock. Figure 2-19 provides a high level view of the AIL methodology.

Figure 2-19. LatticeSC AIL Delay of Input Data Waveform



The AIL slides the acquisition window through the delay chain searching for stable data based solely on data transitions. A specific training pattern is not required to perform this bit alignment, simply data transitions. The size of the acquisition window is user-selectable allowing the AIL to operate over the full range of the PURESPEED I/O range. Based on dynamic user control the AIL can either continuously adjust the window location based on data edge detection or it can be locked to a specific delay.

The AIL operates on single data and double data rate interfaces and is available on most FPGA input pins on the LatticeSC device and all buffer types. The AIL block is low power using only 0.003 mW/MHz typical (6 mW @ 2 Gbps) for PRBS 2^7 data. Multiple AIL inputs can be used to create a bus with a FPGA circuit to realign the bus to a common clock cycle. The FPGA circuit to realign the bus is required and is provided by Lattice as a reference design.

For more information on the LatticeSC AIL please refer to TN1158 LatticeSC PURESPEED I/O Adaptive Input Logic User's Guide.

Input DDR/Shift Block

The DDR/Shift block contains registers and associated logic that support DDR and shift register functions using the high-speed clock and the associated transfer to the low-speed clock domain. It functions as a gearbox allowing high-speed incoming data to be passed into the FPGA fabric. Each PIO supports DDR and x2 shift functions. If desired PIOs A and B or C and D can be combined to form x4 shift functions. The PIOs A and C on the left, right and bottom of the device also contain an optional Adaptive Input Logic (AIL) element. This logic automatically aligns incoming data with the clock allowing for easy design of high-speed interfaces. Figure 2-21 shows a simplified block diagram of the shift register block. The shift block in conjunction with the update and clock divider blocks automatically handles the hand off between the low-speed and high-speed clock domains.

Table 2-10. Supported Output Standards[4]

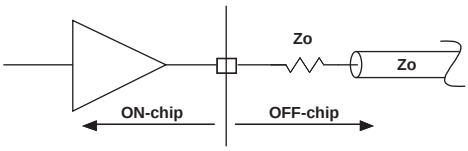
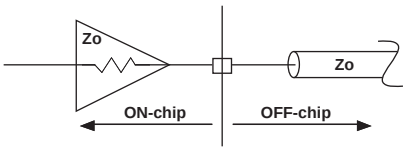
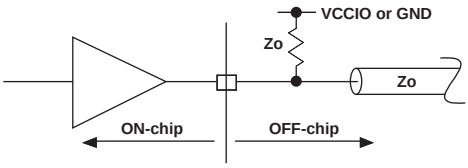
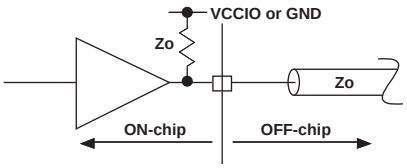
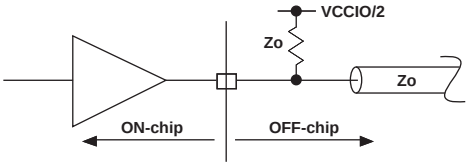
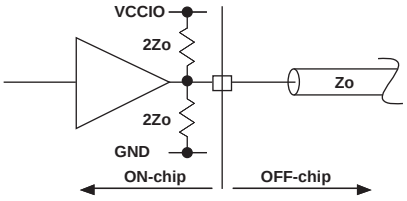
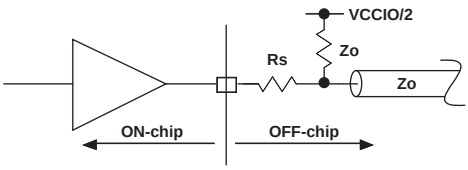
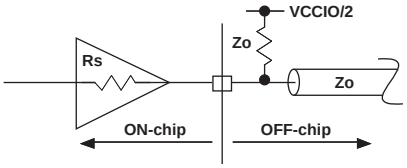
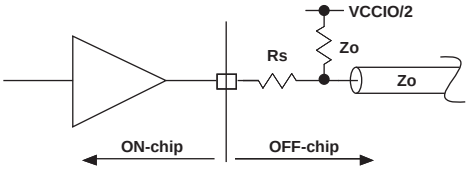
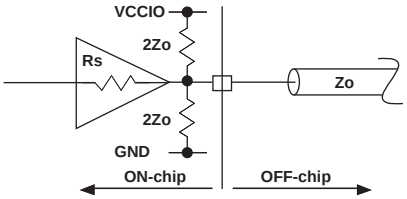
Output Standard	Drive	V_{CCIO} (Nom)	On-chip Output Termination
Single-ended Interfaces			
LVTTL/D[1]	8mA, 16mA, 24mA	3.3	None.
LVCMOS33/D[1]	8mA, 16mA, 24mA	3.3	None
LVCMOS25/D[1, 2]	4mA, 8mA, 12mA, 16mA,	2.5	None, series: 25, 33, 50, 100
LVCMOS18/D[1, 2]	4mA, 8mA, 12mA, 16mA,	1.8	None, series: 25, 33, 50, 100
LVCMOS15/D[1, 2]	4mA, 8mA, 12mA, 16mA,	1.5	None, series: 25, 33, 50, 100
LVCMOS12/D[1, 2]	2mA, 4mA, 8mA, 12mA	1.2	None, series: 25, 33, 50, 100
PCIX15	N/A	1.5	None
PCI33, PCIX33, AGP1X33, AGP2X33	N/A	3.3	None
HSTL18_I	N/A	1.8	None, series: 50
HSTL18_II	N/A	1.8	None, series: 25, series + parallel to V_{CCIO}/2: 25 + 60
HSTL15_I	N/A	1.5	None, series: 50
HSTL15_II	N/A	1.5	None, series: 25, series + parallel to V_{CCIO}/2: 25 + 60
SSTL33_I	N/A	3.3	None
SSTL33_II	N/A	3.3	None
SSTL25_I	N/A	2.5	None, series: 50
SSTL25_II	N/A	2.5	None, series: 33, series + parallel to V_{CCIO}/2: 33+ 60
SSTL18_ I	N/A	1.8	None, series: 33
SSTL18_II	N/A	1.8	None, series: 33, series + parallel to V_{CCIO}/2: 33+ 60
Differential Interfaces			
SSTL18D_I	N/A	1.8	None, series: 33
SSTL25D_I	N/A	2.5	None, series: 50
SSTL18D_II, SSTL25D_II	N/A	1.2/2.5/3.3	None, series: 33, series + parallel to V_{CCIO}/2: 33+ 60
SSTL33D_I, II	N/A	3.3	None
HSTL15D_I, HSTL18D_I	N/A	1.5/1.8	None, series: 50
HST15D_II, HSTL18D_II	N/A	1.5/1.8	None, series: 25, series + parallel to V_{CCIO}/2: 25 + 60
LVDS	2mA, 3.5mA, 4mA, 6mA	N/A	None
Mini-LVDS	3.5mA, 4mA, 6mA	N/A	None
BLVDS25	N/A	N/A	None
MLVDS25	N/A	N/A	None
LVPECL33[3]	N/A	3.3	None
RSDS	2mA, 3.5mA, 4mA, 6mA	N/A	None

1. D refers to open drain capability.
2. User can select either drive current or driver impedances but not both.
3. Emulated with external resistors.
4. No GTL or GTL+ support.

PCI Clamp

A programmable PCI clamp is available on the top and bottom banks of the device. The PCI clamp can be turned “ON” or “OFF” on each pin independently. The PCI clamp is used when implementing a 3.3V PCI interface. The

Figure 2-27. Output Termination Schemes

Termination Type	Discrete Off-Chip Solution	Lattice On-Chip Solution
Series termination (controlled output impedance)		
Parallel termination to V_{CCIO}, or parallel driving end		
Parallel termination to $V_{CCIO}/2$ driving end		
Combined series + parallel termination to $V_{CCIO}/2$ at driving end (only series termination moved on-chip)		
Combined series + parallel to $V_{CCIO}/2$ driving end		

- 8-bit SERDES Only
- 10-bit SERDES Only
- SONET (STS-12/STS-48)
- Gigabit Ethernet
- Fibre Channel
- XAUI
- Serial RapidIO
- PCI-Express
- Generic 8b10b

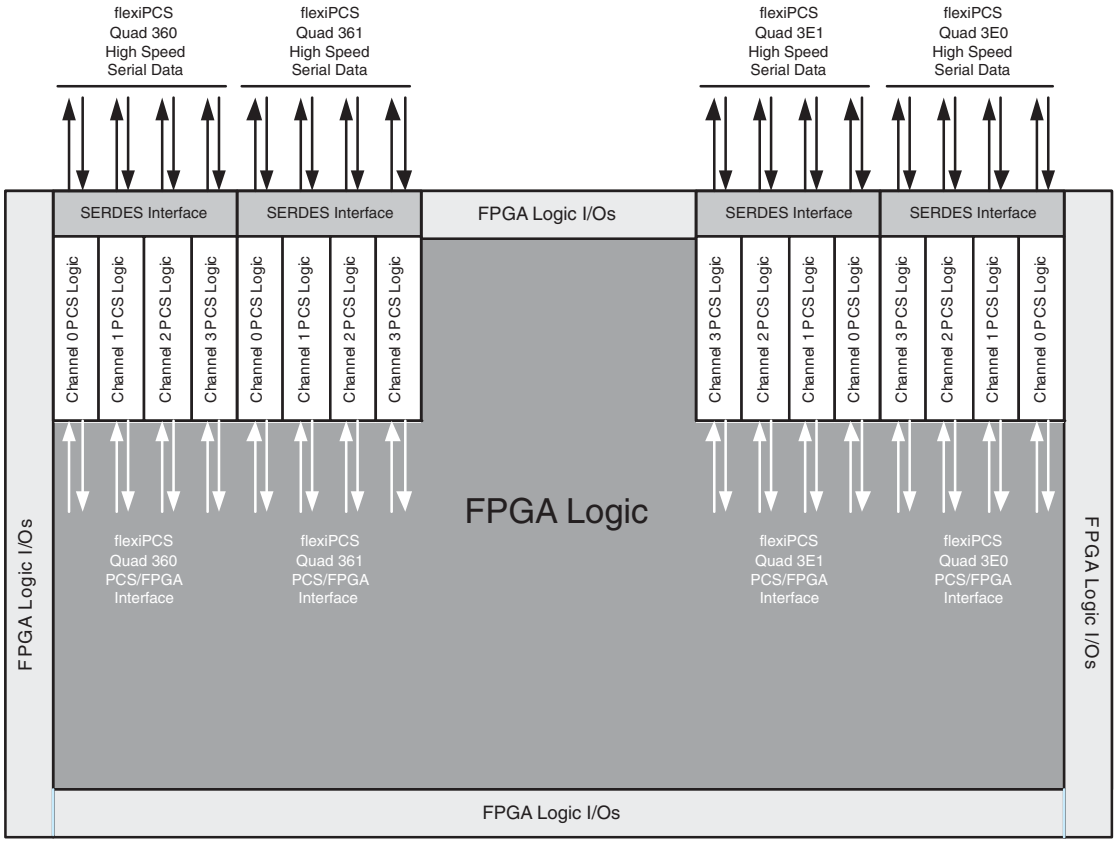
flexiPCS Quad

The flexiPCS logic is arranged in quads containing logic for four independent full-duplex data channels. Each device in the LatticeSC family has up to eight quads of flexiPCS logic. The LatticeSC Family Selection Guide table on the first page of this data sheet contains the number of flexiPCS channels present on the chip. Note that in some packages (particularly lower pin count packages), not all channels from all quads on a given device may be bonded to package pins.

Each quad supports up to four channels of full-duplex data and can be programmed into any one of several protocol based modes. Each quad requires its own reference clock which can be sourced externally or from the FPGA logic. The user can utilize between one and four channels in a quad, depending on the application.

Figure 2-30 shows an example of four flexiPCS quads in a LatticeSC device. Quads are labeled according to the address of their software controlled registers.

Figure 2-30. LatticeSC flexiPCS



Since each quad has its own reference clock, different quads can support different standards on the same chip. This feature makes the LatticeSC family of devices ideal for bridging between different standards.

flexiPCS quads are not dedicated solely to industry standard protocols. Each quad (and each channel within a quad) can be programmed for many user defined data manipulation modes. For example, modes governing user-defined word alignment and multi-channel alignment can be programmed for non-standard protocol applications.

For more information on the functions and use of the flexiPCS, refer to the LatticeSC/M Family flexiPCS Data Sheet.

System Bus

Each LatticeSC device connects the FPGA elements with a standardized bus framework referred to as a System Bus. Multiple bus masters optimize system performance by sharing resources between different bus masters such as the MPI and configuration logic. The wide data bus configuration of 32 bits with 4-bit parity supports high-bandwidth, data intensive applications.

There are two types of interfaces on the System Bus, master and slave. A master interface has the ability to perform actions on the bus, such as writes and reads to and from a specific address. A slave interface responds to the actions of a master by accepting data and address on a write and providing data on a read. The System Bus has a memory map which describes each of the slave peripherals that is connected on the bus. Using the addresses listed in the memory map, a master interface can access each of the slave peripherals on the System Bus. Any and all peripherals on the System Bus can be used at the same time. Table 2-12 list all of the available user peripherals on the System Bus after device power-up.

Table 2-12. System Bus User Peripherals

Peripheral	Name	Interface Type
Micro Processor Interface	MPI	Master
User Master Interface	UMI	Master
User Slave Interface	USI	Slave
Serial Management Interface (PLL, DLL, User Logic)	SMI	Slave
Physical Coding Sublayer	PCS	Slave
Direct FPGA Access	DFA	Slave

The peripherals listed in Table 2-12 can be added when the System Bus module is created using Module IP/Manager (ispLEVER Module/IP Manager).

Figure 2-31 also lists the existing peripherals on the System Bus. The gray boxes are available only during configuration. Refer to Lattice technical note TN1080, LatticeSC sysCONFIG Usage Guide, for configuration options. The Status and Config box refers to internal System Bus registers. This document presents all the interfaces listed in Table 2-12 in detail to help the user utilize the desired functions of the System Bus.

RSDS

Over Recommended Operating Conditions

Parameter Symbol	Description	Min.	Typ.	Max.	Units
V_{OD}	Output voltage, differential, R_T = 100 ohms	100	200	600	mV
V_{OS}	Output voltage, common mode	0.5	1.2	1.5	V
I_{RSDS}	Differential driver output current	1	2	6	mA
V_{THD}	Input voltage differential	100	—	—	mV
V_{CM}	Input common mode voltage	0.3	—	1.5	V
T_R, T_F	Output rise and fall times, 20% to 80%	—	500	—	ps
T_{ODUTY}	Output clock duty cycle	45	50	55	%

Note: Data is for 2mA drive. Other differential driver current options are available.

LatticeSC/M Internal Timing Parameters[1]

Over Recommended Commercial Operating Conditions at VCC = 1.2V +/- 5%

Parameter	Symbol	Description	-7		-6		-5		Units
			Min.	Max.	Min.	Max.	Min.	Max.	
PFU Logic Mode Timing									
t_{LUT4_PFU}	CTOF_DEL	LUT4 delay (A to D inputs to F output)	—	0.045	—	0.050	—	0.054	ns
t_{LUT5_PFU}	MTOOFX_DEL	LUT5 delay (inputs to output)	—	0.152	—	0.172	—	0.192	ns
t_{LSR_PFU}	LSR_DEL	Set/Reset to output (asynchronous)	—	0.378	—	0.426	—	0.474	ns
t_{SUM_PFU}	M_SET	Clock to Mux (M0,M1) input setup time	0.113	—	0.131	—	0.148	—	ns
t_{HM_PFU}	M_HLD	Clock to Mux (M0,M1) input hold time	-0.041	—	-0.046	—	-0.052	—	ns
t_{SUD_PFU}	DIN_SET	Clock to D input setup time	0.072	—	0.083	—	0.094	—	ns
t_{HD_PFU}	DIN_HLD	Clock to D input hold time	-0.028	—	-0.032	—	-0.035	—	ns
t_{CK2Q_PFU}	REG_DEL	Clock to Q delay, D-type register configuration	—	0.224	—	0.252	—	0.279	ns
t_{LE2Q_PFU}	LTCH_DEL	Clock to Q delay latch configuration	—	0.294	—	0.331	—	0.367	ns
t_{LD2Q_PFU}	TLTCH_DEL	D to Q throughput delay when latch is enabled	—	0.300	—	0.338	—	0.376	ns
PFU Memory Mode Timing									
t_{CORAM_PFU}	CLKTOF_DEL	Clock to Output	—	0.575	—	0.649	—	0.724	ns
t_{SUDATA_PFU}	DIN_SET	Data Setup Time	-0.024	—	-0.026	—	-0.027	—	ns
t_{HDATA_PFU}	DIN_HLD	Data Hold Time	0.075	—	0.084	—	0.094	—	ns
t_{SUADDR_PFU}	WAD_SET	Address Setup Time	-0.176	—	-0.196	—	-0.215	—	ns
t_{HADDR_PFU}	WAD_HLD	Address Hold Time	0.110	—	0.124	—	0.138	—	ns
t_{SUWREN_PFU}	WE_SET	Write/Read Enable Setup Time	0.014	—	0.019	—	0.024	—	ns
t_{HWREN_PFU}	WE_HLD	Write/Read Enable Hold Time	0.078	—	0.086	—	0.094	—	ns
PIC Timing									
PIO Input/Output Buffer Timing									
t_{IN_PIO}	IN_DEL	Input Buffer Delay(LVCMOS25)	—	0.578	—	0.661	—	0.744	ns
t_{OUT_PIO}	DOPADI_DEL	Output Buffer Delay(LVCMOS25)	—	2.712	—	3.027	—	3.395	ns
t_{SUI_PIO}	DIN_SET	Input Register Setup Time (Data Before Clock)	0.277	—	0.312	—	0.348	—	ns
t_{HI_PIO}	DIN_HLD	Input Register Hold Time (Data after Clock)	-0.267	—	-0.306	—	-0.345	—	ns
t_{COO_PIO}	CK_DEL	Output Register Clock to Output Delay	—	0.513	—	0.571	—	0.639	ns
t_{SUCE_PIO}	CE_SET	Input Register Clock Enable Setup Time	—	0.000	—	0.000	—	0.000	ns
t_{HCE_PIO}	CE_HLD	Input Register Clock Enable Hold Time	—	0.129	—	0.145	—	0.161	ns
t_{SULSR_PIO}	LSR_SET	Set/Reset Setup Time	0.057	—	0.060	—	0.063	—	ns
t_{HLSR_PIO}	LSR_HLD	Set/Reset Hold Time	-0.151	—	-0.159	—	-0.169	—	ns
t_{LE2Q_PIO}	CK_DEL	Input Register Clock to Q delay latch configuration	—	0.335	—	0.372	—	0.410	ns
t_{LD2Q_PIO}	DIN_DEL	Input Register D to Q throughput delay when latch is enabled	—	0.578	—	0.647	—	0.717	ns

LatticeSC/M sysCONFIG Port Timing

Over Recommended Operating Conditions

Parameter	Description	Min.	Max.	Units
General Configuration Timing				
t_{SMODE}	M[3:0] Setup Time to INITN High	0	—	ns
t_{HMODE}	M[3:0] Hold Time from INITN High	600	—	ns
t_{RW}	RESETN Pulse Width Low to Start Reconfiguration (1.2 V)	50 (or 100 at 0.95V)	—	ns
t_{PGW}	PROGRAMN Pulse Width Low to Start Reconfiguration (1.2 V)	50 (or 100 at 0.95V)	—	ns
$f_{ESB\_CLK\_FRQ}$	System Bus ESB_CLK Frequency (No Wait States)	—	133	MHz
sysCONFIG Master Parallel Configuration Mode				
t_{SMB}	D[7:0] Setup Time to RCLK High	6	—	ns
t_{HMB}	D[7:0] Hold Time to RCLK High	0	—	ns
t_{CLMB}	RCLK Low Time (Non-compressed Bitstreams)	0.5	0.5	CCLK periods
	RCLK Low Time (Compressed Bitstreams)	0.5	7.5	CCLK periods
t_{CHMB}	RCLK High Time	0.5	0.5	CCLK periods
sysCONFIG SPI Port				
t_{CFGX}	INITN High to CSCK Low	—	80	ns
t_{CSSPI}	INITN High to CSSPIN Low	0	2	µs
t_{SCK}	CSCK Low before CSSPIN Low	0	—	ns
t_{SOCDO}	CSCK Low to Output Valid	—	15	ns
t_{CSPID}	CSSPIN Low to CSCK high Setup Time	—	15	ns
f_{MAXSPI}	Max CCLK Frequency - SPI Flash Fast Read Opcode (0x0B) (SPIFASTN=0)	—	50	MHz
t_{SUSPI}	SOSPI/D0 Data Setup Time Before CSCK	7	—	ns
t_{HSPI}	SOSPI/D0 Data Hold Time After CSCK	2	—	ns
	Master Clock Frequency	Selected value - 30%	Selected value + 30%	MHz
	Duty Cycle	40	60	%
sysCONFIG Master Serial Configuration Mode				
t_{SMS}	DIN Setup Time	4.4	—	ns
t_{HMS}	DIN Hold Time	0	—	ns
f_{CMS}	CCLK Frequency (No Divider)	90	190	MHz
f_{C_DIV}	CCLK Frequency (Div 128)	0.70	1.48	MHz
t_{D}	CCLK to DOUT Delay	—	7.5	ns
sysCONFIG Master Parallel Configuration Mode				
t_{AVMP}	RCLK to Address Valid	—	10	ns
t_{SMP}	D[7:0] Setup Time to RCLK High	6	—	ns
t_{HMP}	D[7:0] Hold Time to RCLK High	0	—	ns
t_{CLMP}	RCLK Low Time (Non-compressed Bitstream)	7.5	7.5	CCLK periods
	RCLK Low Time (Compressed Bitstream)	0.5	63.5	
t_{CHMP}	RCLK High Time	0.5	0.5	CCLK periods
t_{DMP}	CCLK to DOUT	—	7.5	ns

Signal Descriptions (Cont.)

Signal Name	I/O	Description
PROBE_GND	—	GND signal - Connected to internal VSS node. Can be used for feedback to control an external board power converter. Can be unconnected if not used.
PLL and Clock Functions (Used as user-programmable I/O pins when not in use for PLL, DLL or clock pins.)		
[LOC]_PLL[T, C]_FB_[A/B]	I	PLL feedback input. Pull-ups are enabled on input pins during configuration. [LOC] indicates the corner the PLL is located in: ULC (upper left), URC (upper right), LLC (lower left) and LRC (lower right). [T, C] indicates whether input is true or complement. [A, B] indicates PLL reference within the corner.
[LOC]_DLL[T, C]_FB_[C, D, E, F]	I	DLL feedback input. Pull-ups are enabled on input pins during configuration. [LOC] indicates the corner the DLL is located in: ULC (upper left), URC (upper right), LLC (lower left) and LRC (lower right). [T/C] indicates whether input is true or complement. [C, D, E, F] indicates DLL reference within a corner. Note: E and F are only available on the lower corners.
[LOC]_PLL[T, C]_IN[A/B]	I	PLL reference clock input. Pull-ups are enabled on input pins during configuration. [LOC] indicates the corner the PLL is located in: ULC (upper left corner), URC (upper right corner), LLC (lower left corner) and LRC (lower right corner). [T, C] indicates whether input is true or complement.[A, B] indicates PLL reference within the corner.
[LOC]_DLL[T, C]_IN[C, D, E, F]		DLL reference clock inputs. Pull-ups are enabled on input pins during configuration. [LOC] indicates the corner the DLL is located in: ULC (upper left corner), URC (upper right corner), LLC (lower left corner) and LRC (lower right corner). [T/C] indicates whether input is true or complement. [C, D, E, F] indicates DLL reference within a corner. Note: E and F are only available on the lower corners. PCKLxy_[0:3] can drive primary clocks, edge clocks, and CLKDIVs. PCLKxy_[4:7] can only drive edge clocks.
PCLKxy_z		General clock inputs. x indicates whether T (true) or C (complement). y indicates the I/O bank the clock is associated with. z indicates the clock number within a bank.
Test and Programming (Dedicated pins. Pull-up is enabled on input pins during configuration.)		
TMS	I	Test Mode Select input, used to control the 1149.1 state machine.
TCK	I	Test Clock input pin, used to clock the 1149.1 state machine.
TDI	I	Test Data in pin, used to load data into device using 1149.1 state machine. After power-up, this TAP port can be activated for configuration by sending appropriate command. (Note: once a configuration port is selected it is locked. Another configuration port cannot be selected until the power-up sequence).
TDO	O	Output pin -Test Data out pin used to shift data out of device using 1149.1.
Configuration Pads (Dedicated pins. Used during sysCONFIG.)		
M[3:0]	I	Mode pins used to specify configuration modes values latched on rising edge of INITN.
INITN	I/O	Open Drain pin - Indicates the FPGA is ready to be configured. During configuration, a pull-up is enabled that will pull the I/O above 1.5V.
PROGRAMN	I	Initiates configuration sequence when asserted low. This pin always has an active pull-up.
DONE	I/O	Open Drain pin - Indicates that the configuration sequence is complete, and the startup sequence is in progress.
CCLK	I/O	Configuration Clock for configuring an FPGA in sysCONFIG mode.

LFSC/M15 Logic Signal Connections: 256 fpBGA[1,2] (Cont.)

Ball Number	LFSC/M15		
	Ball Function	VCCIO Bank	Dual Function
C5	A_VDDIB1_L	-	
A5	A_HDINP1_L	-	PCS 360 CH 1 IN P
B5	A_HDINN1_L	-	PCS 360 CH 1 IN N
A4	A_HDOUTP1_L	-	PCS 360 CH 1 OUT P
B4	A_HDOUTN1_L	-	PCS 360 CH 1 OUT N
C4	A_VDDOB1_L	-	
B3	A_HDOUTN0_L	-	PCS 360 CH 0 OUT N
C3	A_VDDOB0_L	-	
A3	A_HDOUTP0_L	-	PCS 360 CH 0 OUT P
B2	A_HDINN0_L	-	PCS 360 CH 0 IN N
A2	A_HDINP0_L	-	PCS 360 CH 0 IN P
C2	A_VDDIB0_L	-	
A1	GND	-	
A16	GND	-	
B10	GND	-	
C13	GND	-	
D15	GND	-	
D3	GND	-	
E11	GND	-	
F13	GND	-	
G14	GND	-	
G2	GND	-	
G8	GND	-	
H10	GND	-	
J7	GND	-	
K15	GND	-	
K3	GND	-	
K9	GND	-	
M6	GND	-	
N11	GND	-	
N14	GND	-	
N2	GND	-	
P10	GND	-	
P4	GND	-	
R13	GND	-	
R7	GND	-	
G10	VCC	-	
G7	VCC	-	
G9	VCC	-	
H7	VCC	-	
H8	VCC	-	
H9	VCC	-	
J10	VCC	-	
J8	VCC	-	

LFSC/M15, LFSC/M25 Logic Signal Connections: 900 fpBGA[1, 2] (Cont.)

Ball Number	LFSC/M15			LFSC/M25		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
U18	GND	-		GND	-	
U19	GND	-		GND	-	
U20	GND	-		GND	-	
V11	GND	-		GND	-	
V12	GND	-		GND	-	
V13	GND	-		GND	-	
V14	GND	-		GND	-	
V15	GND	-		GND	-	
V16	GND	-		GND	-	
V17	GND	-		GND	-	
V18	GND	-		GND	-	
V19	GND	-		GND	-	
V20	GND	-		GND	-	
W11	GND	-		GND	-	
W12	GND	-		GND	-	
W13	GND	-		GND	-	
W14	GND	-		GND	-	
W15	GND	-		GND	-	
W16	GND	-		GND	-	
W17	GND	-		GND	-	
W18	GND	-		GND	-	
W19	GND	-		GND	-	
W20	GND	-		GND	-	
Y11	GND	-		GND	-	
Y12	GND	-		GND	-	
Y13	GND	-		GND	-	
Y14	GND	-		GND	-	
Y15	GND	-		GND	-	
Y16	GND	-		GND	-	
Y17	GND	-		GND	-	
Y18	GND	-		GND	-	
Y19	GND	-		GND	-	
Y20	GND	-		GND	-	
H2	VCCIO7	-		VCCIO7	-	
N4	VCCIO7	-		VCCIO7	-	
N6	VCCIO7	-		VCCIO7	-	
J2	VCCIO7	-		VCCIO7	-	
L2	VCCIO7	-		VCCIO7	-	
H4	VCCIO7	-		VCCIO7	-	
AB2	VCCIO6	-		VCCIO6	-	
AD1	VCCIO6	-		VCCIO6	-	
W4	VCCIO6	-		VCCIO6	-	
AA4	VCCIO6	-		VCCIO6	-	
AE7	VCCIO5	-		VCCIO5	-	
AH6	VCCIO5	-		VCCIO5	-	

LFSC/M25, LFSC/M40 Logic Signal Connections: 1020 fcBGA[1, 2] (Cont.)

Ball Number	LFSC/M25			LFSC/M40		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
Y24	PL48C	6		PL61C	6	
Y23	PL48D	6		PL61D	6	
AD29	PL49A	6		PL62A	6	
AD30	PL49B	6		PL62B	6	
AF28	PL49C	6		PL62C	6	
AE28	PL49D	6		PL62D	6	
AC28	PL51A	6		PL65A	6	
AD28	PL51B	6		PL65B	6	
AB26	PL51C	6		PL65C	6	
AC26	PL51D	6	VREF2_6	PL65D	6	VREF2_6
AC32	PL52A	6		PL66A	6	
AD32	PL52B	6		PL66B	6	
AA24	PL52C	6		PL66C	6	
AA23	PL52D	6		PL66D	6	
AE30	PL53A	6		PL67A	6	
AE29	PL53B	6		PL67B	6	
AC25	PL53C	6		PL67C	6	
AB25	PL53D	6		PL67D	6	
AE31	PL55A	6		PL69A	6	
AE32	PL55B	6		PL69B	6	
AE26	PL55C	6	LLC_DLLT_IN_E/LLC_DLLT_FB_F	PL69C	6	LLC_DLLT_IN_E/LLC_DLLT_FB_F
AE27	PL55D	6	LLC_DLLC_IN_E/LLC_DLLC_FB_F	PL69D	6	LLC_DLLC_IN_E/LLC_DLLC_FB_F
AF32	PL56A	6		PL70A	6	
AF31	PL56B	6		PL70B	6	
AC24	PL56C	6		PL70C	6	
AD25	PL56D	6		PL70D	6	
AG32	PL57A	6	LLC_DLLT_IN_F/LLC_DLLT_FB_E	PL71A	6	LLC_DLLT_IN_F/LLC_DLLT_FB_E
AG31	PL57B	6	LLC_DLLC_IN_F/LLC_DLLC_FB_E	PL71B	6	LLC_DLLC_IN_F/LLC_DLLC_FB_E
AC23	PL57C	6	LLC_PLLT_IN_B/LLC_PLLT_FB_A	PL71C	6	LLC_PLLT_IN_B/LLC_PLLT_FB_A
AD24	PL57D	6	LLC_PLLC_IN_B/LLC_PLLC_FB_A	PL71D	6	LLC_PLLC_IN_B/LLC_PLLC_FB_A
AH32	XRES	-		XRES	-	
AH31	TEMP	6		TEMP	6	
AJ32	PB3A	5	LLC_PLLT_IN_A/LLC_PLLT_FB_B	PB3A	5	LLC_PLLT_IN_A/LLC_PLLT_FB_B
AK32	PB3B	5	LLC_PLLC_IN_A/LLC_PLLC_FB_B	PB3B	5	LLC_PLLC_IN_A/LLC_PLLC_FB_B
AF27	PB3C	5	LLC_DLLT_IN_C/LLC_DLLT_FB_D	PB3C	5	LLC_DLLT_IN_C/LLC_DLLT_FB_D
AG28	PB3D	5	LLC_DLLC_IN_C/LLC_DLLC_FB_D	PB3D	5	LLC_DLLC_IN_C/LLC_DLLC_FB_D
AK31	PB4A	5	LLC_DLLT_IN_D/LLC_DLLT_FB_C	PB4A	5	LLC_DLLT_IN_D/LLC_DLLT_FB_C
AL31	PB4B	5	LLC_DLLC_IN_D/LLC_DLLC_FB_C	PB4B	5	LLC_DLLC_IN_D/LLC_DLLC_FB_C
AE25	PB4C	5		PB4C	5	
AE24	PB4D	5		PB4D	5	
AK30	PB5A	5		PB5A	5	
AL30	PB5B	5		PB5B	5	
AD23	PB5C	5		PB5C	5	
AE23	PB5D	5	VREF1_5	PB5D	5	VREF1_5
AK29	PB7A	5		PB7A	5	
AL29	PB7B	5		PB7B	5	
AF26	PB7C	5		PB7C	5	
AF25	PB7D	5		PB7D	5	
AJ28	PB8A	5		PB8A	5	
AK28	PB8B	5		PB8B	5	

LFSC/M115 Logic Signal Connections: 1152 fcBGA[1, 2]

Ball Number	LFSC/M115		
	Ball Function	VCCIO Bank	Dual Function
AL4	PR117B	3	LRC_DLLC_IN_F/LRC_DLLC_FB_E
AL3	PR117A	3	LRC_DLLT_IN_F/LRC_DLLT_FB_E
AD10	PR116D	3	
AD9	PR116C	3	
AH4	PR116B	3	
AJ4	PR116A	3	
AK5	PR115D	3	LRC_DLLC_IN_E/LRC_DLLC_FB_F
AJ5	PR115C	3	LRC_DLLT_IN_E/LRC_DLLT_FB_F
AM1	PR115B	3	
AL1	PR115A	3	
AH5	PR112D	3	
AG5	PR112C	3	
AL2	PR112B	3	
AK2	PR112A	3	
AB9	PR109D	3	
AC9	PR109C	3	
AH1	PR109B	3	
AG1	PR109A	3	
AE8	PR107D	3	VREF2_3
AD8	PR107C	3	
AJ3	PR107B	3	
AH3	PR107A	3	
AD7	PR104D	3	
AC7	PR104C	3	
AJ2	PR104B	3	
AH2	PR104A	3	
AF6	PR103D	3	
AF5	PR103C	3	
AF4	PR103B	3	
AE4	PR103A	3	
AD6	PR99D	3	
AC6	PR99C	3	
AG2	PR99B	3	
AF2	PR99A	3	
AC8	PR98D	3	
AB8	PR98C	3	
AK1	PR98B	3	
AJ1	PR98A	3	
AB10	PR96D	3	
AA10	PR96C	3	
AF3	PR96B	3	
AE3	PR96A	3	
AE5	PR94D	3	

LFSC/M80, LFSC/M115 Logic Signal Connections: 1704 fcBGA[1, 2] (Cont.)

Ball Number	LFSC/M80			LFSC/M115		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
W33	PL42C	7		PL56C	7	
Y33	PL42D	7		PL56D	7	
W37	PL43A	7		PL57A	7	
Y37	PL43B	7		PL57B	7	
Y32	PL43C	7		PL57C	7	
AA32	PL43D	7		PL57D	7	
U38	PL46A	7		PL60A	7	
V38	PL46B	7		PL60B	7	
W34	PL46C	7		PL60C	7	
Y34	PL46D	7		PL60D	7	
T40	PL47A	7	PCLKT7_1	PL61A	7	PCLKT7_1
U40	PL47B	7	PCLKC7_1	PL61B	7	PCLKC7_1
AA33	PL47C	7	PCLKT7_3	PL61C	7	PCLKT7_3
AB33	PL47D	7	PCLKC7_3	PL61D	7	PCLKC7_3
R42	PL48A	7	PCLKT7_0	PL62A	7	PCLKT7_0
T42	PL48B	7	PCLKC7_0	PL62B	7	PCLKC7_0
AA34	PL48C	7	PCLKT7_2	PL62C	7	PCLKT7_2
AB34	PL48D	7	PCLKC7_2	PL62D	7	PCLKC7_2
U41	PL50A	6	PCLKT6_0	PL64A	6	PCLKT6_0
V41	PL50B	6	PCLKC6_0	PL64B	6	PCLKC6_0
V36	PL50C	6	PCLKT6_1	PL64C	6	PCLKT6_1
W36	PL50D	6	PCLKC6_1	PL64D	6	PCLKC6_1
U42	PL51A	6		PL65A	6	
V42	PL51B	6		PL65B	6	
AB31	PL51C	6	PCLKT6_3	PL65C	6	PCLKT6_3
AC31	PL51D	6	PCLKC6_3	PL65D	6	PCLKC6_3
W38	PL52A	6		PL66A	6	
Y38	PL52B	6		PL66B	6	
AA35	PL52C	6	PCLKT6_2	PL66C	6	PCLKT6_2
AB35	PL52D	6	PCLKC6_2	PL66D	6	PCLKC6_2
W39	PL55A	6		PL69A	6	
Y39	PL55B	6		PL69B	6	
AB32	PL55C	6	VREF1_6	PL69C	6	VREF1_6
AC32	PL55D	6		PL69D	6	
W40	PL56A	6		PL70A	6	
Y40	PL56B	6		PL70B	6	
AA36	PL56C	6		PL70C	6	
AB36	PL56D	6		PL70D	6	
W41	PL57A	6		PL71A	6	
Y41	PL57B	6		PL71B	6	
AA37	PL57C	6		PL71C	6	
AB37	PL57D	6		PL71D	6	
W42	PL59A	6		PL73A	6	
Y42	PL59B	6		PL73B	6	
AC33	PL59C	6		PL73C	6	

LFSC/M80, LFSC/M115 Logic Signal Connections: 1704 fcBGA[1, 2] (Cont.)

Ball Number	LFSC/M80			LFSC/M115		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
B22	PT61B	1	A3/MPI_ADDR17	PT69B	1	A3/MPI_ADDR17
B23	PT61A	1	A4/MPI_ADDR18	PT69A	1	A4/MPI_ADDR18
K23	PT60D	1	D25/PCLKC1_5/MPI_DATA25	PT66D	1	D25/PCLKC1_5/MPI_DATA25
J23	PT60C	1	D26/PCLKT1_5/MPI_DATA26	PT66C	1	D26/PCLKT1_5/MPI_DATA26
D22	PT60B	1	A5/MPI_ADDR19	PT66B	1	A5/MPI_ADDR19
E22	PT60A	1	A6/MPI_ADDR20	PT66A	1	A6/MPI_ADDR20
K22	PT59D	1	D27/MPI_DATA27	PT63D	1	D27/MPI_DATA27
J22	PT59C	1	VREF1_1	PT63C	1	VREF1_1
D23	PT59B	1	A7/MPI_ADDR21	PT63B	1	A7/MPI_ADDR21
C23	PT59A	1	A8/MPI_ADDR22	PT63A	1	A8/MPI_ADDR22
L23	PT57D	1	D28/PCLKC1_6/MPI_DATA28	PT61D	1	D28/PCLKC1_6/MPI_DATA28
M23	PT57C	1	D29/PCLKT1_6/MPI_DATA29	PT61C	1	D29/PCLKT1_6/MPI_DATA29
A24	PT57B	1	A9/MPI_ADDR23	PT61B	1	A9/MPI_ADDR23
B24	PT57A	1	A10/MPI_ADDR24	PT61A	1	A10/MPI_ADDR24
K25	PT56D	1	D30/PCLKC1_7/MPI_DATA30	PT58D	1	D30/PCLKC1_7/MPI_DATA30
J25	PT56C	1	D31/PCLKT1_7/MPI_DATA31	PT58C	1	D31/PCLKT1_7/MPI_DATA31
F23	PT56B	1	A11/MPI_ADDR25	PT58B	1	A11/MPI_ADDR25
F22	PT56A	1	A12/MPI_ADDR26	PT58A	1	A12/MPI_ADDR26
J26	PT55D	1	D11/MPI_DATA11	PT57D	1	D11/MPI_DATA11
K26	PT55C	1	D12/MPI_DATA12	PT57C	1	D12/MPI_DATA12
E23	PT55B	1	A13/MPI_ADDR27	PT57B	1	A13/MPI_ADDR27
E24	PT55A	1	A14/MPI_ADDR28	PT57A	1	A14/MPI_ADDR28
G23	PT53D	1	A16/MPI_ADDR30	PT55D	1	A16/MPI_ADDR30
G24	PT53C	1	D13/MPI_DATA13	PT55C	1	D13/MPI_DATA13
F26	PT53B	1	A15/MPI_ADDR29	PT55B	1	A15/MPI_ADDR29
F27	PT53A	1	A17/MPI_ADDR31	PT55A	1	A17/MPI_ADDR31
H25	PT52D	1	A19/MPI_TSIZ1	PT54D	1	A19/MPI_TSIZ1
H24	PT52C	1	A20/MPI_BDIP	PT54C	1	A20/MPI_BDIP
C25	PT52B	1	A18/MPI_TSIZ0	PT54B	1	A18/MPI_TSIZ0
C26	PT52A	1	MPI_TEA	PT54A	1	MPI_TEA
K24	PT51D	1	D14/MPI_DATA14	PT51D	1	D14/MPI_DATA14
J24	PT51C	1	DP1/MPI_PAR1	PT51C	1	DP1/MPI_PAR1
F24	PT51B	1	A21/MPI_BURST	PT51B	1	A21/MPI_BURST
F25	PT51A	1	D15/MPI_DATA15	PT51A	1	D15/MPI_DATA15
L26	D_REFCLKP_L	-		D_REFCLKP_L	-	
M26	D_REFCLKN_L	-		D_REFCLKN_L	-	
G27	VCC12	-		VCC12	-	
C29	D_VDDIB3_L	-		D_VDDIB3_L	-	
F28	VCC12	-		VCC12	-	
D26	D_HDINP3_L	-	PCS 363 CH 3 IN P	D_HDINP3_L	-	PCS 363 CH 3 IN P
E26	D_HDINN3_L	-	PCS 363 CH 3 IN N	D_HDINN3_L	-	PCS 363 CH 3 IN N
B25	D_HDOUTP3_L	-	PCS 363 CH 3 OUT P	D_HDOUTP3_L	-	PCS 363 CH 3 OUT P
D24	VCC12	-		VCC12	-	
A25	D_HDOUTN3_L	-	PCS 363 CH 3 OUT N	D_HDOUTN3_L	-	PCS 363 CH 3 OUT N
E25	D_VDDOB3_L	-		D_VDDOB3_L	-	

LFSC/M80, LFSC/M115 Logic Signal Connections: 1704 fcBGA[1, 2] (Cont.)

Ball Number	LFSC/M80			LFSC/M115		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
AG38	NC	-		PL95A	6	
AH38	NC	-		PL95B	6	
AJ39	NC	-		PL100A	6	
AK39	NC	-		PL100B	6	
AL41	NC	-		PL105A	6	
AM41	NC	-		PL105B	6	
AN40	NC	-		PL108A	6	
AM40	NC	-		PL108B	6	
AM39	NC	-		PL111A	6	
AN39	NC	-		PL111B	6	
AR42	NC	-		PL113A	6	
AT42	NC	-		PL113B	6	
AT1	NC	-		PR113B	3	
AR1	NC	-		PR113A	3	
AN4	NC	-		PR111B	3	
AM4	NC	-		PR111A	3	
AM3	NC	-		PR108B	3	
AN3	NC	-		PR108A	3	
AM2	NC	-		PR105B	3	
AL2	NC	-		PR105A	3	
AK4	NC	-		PR100B	3	
AJ4	NC	-		PR100A	3	
AH5	NC	-		PR95B	3	
AG5	NC	-		PR95A	3	
P6	NC	-		PR39B	2	
N6	NC	-		PR39A	2	
L3	NC	-		PR36B	2	
K3	NC	-		PR36A	2	
M5	NC	-		PR35A	2	
L4	NC	-		PR32B	2	
K4	NC	-		PR32A	2	
A2	GND	-		GND	-	
A41	GND	-		GND	-	
AA20	GND	-		GND	-	
AA23	GND	-		GND	-	
AA3	GND	-		GND	-	
AA39	GND	-		GND	-	
AB20	GND	-		GND	-	
AB23	GND	-		GND	-	
AB4	GND	-		GND	-	
AB40	GND	-		GND	-	
AC17	GND	-		GND	-	
AC19	GND	-		GND	-	
AC21	GND	-		GND	-	
AC22	GND	-		GND	-	

Commercial, Cont.

Part Number	Grade	Package	Balls	Temp.	LUTs (K)
LFSC3GA40E-7FFN1020C[1]	-7	Lead-Free Organic fcBGA	1020	COM	40.4
LFSC3GA40E-6FFN1020C[1]	-6	Lead-Free Organic fcBGA	1020	COM	40.4
LFSC3GA40E-5FFN1020C[1]	-5	Lead-Free Organic fcBGA	1020	COM	40.4
LFSC3GA40E-7FFAN1020C	-7	Lead-Free Organic fcBGA Revision 2	1020	COM	40.4
LFSC3GA40E-6FFAN1020C	-6	Lead-Free Organic fcBGA Revision 2	1020	COM	40.4
LFSC3GA40E-5FFAN1020C	-5	Lead-Free Organic fcBGA Revision 2	1020	COM	40.4
LFSC3GA40E-7FCN1152C[2]	-7	Lead-Free Ceramic fcBGA	1152	COM	40.4
LFSC3GA40E-6FCN1152C[2]	-6	Lead-Free Ceramic fcBGA	1152	COM	40.4
LFSC3GA40E-5FCN1152C[2]	-5	Lead-Free Ceramic fcBGA	1152	COM	40.4
LFSC3GA40E-7FFN1152C	-7	Lead-Free Organic fcBGA	1152	COM	40.4
LFSC3GA40E-6FFN1152C	-6	Lead-Free Organic fcBGA	1152	COM	40.4
LFSC3GA40E-5FFN1152C	-5	Lead-Free Organic fcBGA	1152	COM	40.4

1. Converted to organic flip-chip BGA package revision 2 per PCN #02A-10.
2. Converted to organic flip-chip BGA package per PCN #01A-10.

Part Number	Grade	Package	Balls	Temp.	LUTs (K)
LFSCM3GA40EP1-7FFN1020C[1]	-7	Organic fcBGA	1020	COM	40.4
LFSCM3GA40EP1-6FFN1020C[1]	-6	Organic fcBGA	1020	COM	40.4
LFSCM3GA40EP1-5FFN1020C[1]	-5	Organic fcBGA	1020	COM	40.4
LFSCM3GA40EP1-7FFAN1020C	-7	Organic fcBGA Revision 2	1020	COM	40.4
LFSCM3GA40EP1-6FFAN1020C	-6	Organic fcBGA Revision 2	1020	COM	40.4
LFSCM3GA40EP1-5FFAN1020C	-5	Organic fcBGA Revision 2	1020	COM	40.4
LFSCM3GA40EP1-7FCN1152C[2]	-7	Ceramic fcBGA	1152	COM	40.4
LFSCM3GA40EP1-6FCN1152C[2]	-6	Ceramic fcBGA	1152	COM	40.4
LFSCM3GA40EP1-5FCN1152C[2]	-5	Ceramic fcBGA	1152	COM	40.4
LFSCM3GA40EP1-7FFN1152C	-7	Organic fcBGA	1152	COM	40.4
LFSCM3GA40EP1-6FFN1152C	-6	Organic fcBGA	1152	COM	40.4
LFSCM3GA40EP1-5FFN1152C	-5	Organic fcBGA	1152	COM	40.4

1. Converted to organic flip-chip BGA package revision 2 per PCN #02A-10.
2. Converted to organic flip-chip BGA package per PCN #01A-10.

LatticeSC/M Family Data Sheet Revision History

December 2011 **Data Sheet DS1004**

Date	Version	Section	Change Summary
February 2006	01.0	—	Initial release.
March 2006	01.1	Introduction	SC25 1020 I/O count changed to 476.
		Architecture	Changed ROM 16X4 to ROM 16X2.
			Changed “X2 or X4” to “DIV2 or DIV4”.
			Added Global Set/Reset Section.
		DC and Switching Characteristics	Added notes 5 and 6 to Recommended Operating Conditions table.
			Added Power Supply Ramp Rates table.
			Removed -5 and -6 speed grades from Typical Building Block Performance table.
			Added Input Delay Timing table.
			Added Synchronous GSR Timing table.
		Pinout Information	Expanded PROBE_VCC and PROBE_GND description.
			Removed A-RXREFCLKP_[L/R] from Signal Description table.
			Added RESP_[ULC/URC] to Signal Description table.
			Added notes 1 and 2 to Signal Description table.
			Changed number of NCs to 28.
			Changed number of SERDES (signal + power supply) to 74.
			Removed RESP balls from NC list (B2, C2, B29, C29).
			Added note to VTT table.
			Changed RxRefclk (B2 and C2) to NC.
			Added RESP_ULC.
			Added RESP_URC.
			Changed RxRefclk (B29 and C29) to NC.
June 2006	01.2	Introduction	Changed SERDES min bandwidth from 622 Mbps to 600 Mbps.
			Changed max SERDES bandwidth from 3.4 Gbps to 3.8 Gbps.
			Corrected number of package I/Os for the SC80 and SC115 1704 pin packages.
			Updated speed performance for typical functions with ispLEVER 6.0 values.
		Architecture	Changed “When these pins are not used they should be left unconnected.” with “Unused VTT pins should be connected to GND if the internal or external VCMT function is not used in the bank. If the internal or external VCMT function for differential input termination is used, the VTT pins should be unconnected and allowed to float.”
			Added “SERDES Power Supply Sequencing Requirements” section.
			Changed total bandwidth per quad from 13.6 Gbps to 15.2 Gbps.
			Added the accuracy of the temperature-sensing diode to be typically +/- 10 °C. Also referred to a temperature-sensing diode application note for more information.
		DC and Switching Characteristics	Changed “CTAP” to “internal or external VCMT”.
			Changed VCC12 parameter to include VDDP, VDDTX and VDDRX.
			Changed typical values to match ispLEVER 6.0 Power Calculator.

Date	Version	Section	Change Summary
March 2007 (cont.)	01.5 (cont.)	DC and Switching Characteristics (cont.)	Updated LatticeSC Internal Timing Parameters with ispLEVER 6.1 SP1 results.
			Updated t_{FDEL} and t_{CDEL} specifications.
			Updated LatticeSC Family Timing Adders with ispLEVER 6.1 SP1 results.
			Updated PLL specifications to expand frequency range down to 2 MHz and break out jitter for the different ranges.
			Added footnote to sysCLOCK PLL Timing table specifying the conditions for the jitter measurements.
			Added t_{DLL} specification to sysCLOCK DLL Timing table.
			Added footnote to sysCLOCK DLL Timing table specifying the conditions for the jitter measurements.
			Added sysCONFIG Master Parallel Configuration Mode and sysCONFIG SPI Port to LatticeSC sysCONFIG Port Timing table.
		Pin Information	Updated Pin Information Summary with SC40 information.
			Updated LFSC25 Logic Signal Connections: FF1020 with SC40 information.
			Updated LFSC80 Logic Signal Connections: FC1152 with SC40 information.
August 2007	01.6	General	Changed references of "HDC" to "HDC/SI".
			Changed references of "LDCN" to "LDCN/SCS".
			Changed references of "BUSYN/RCLK" to "BUSYN/RCLK/SCK".
			Changed references of "RDCFGN" to "TSALLN".
			Changed references of "TDO/RDDATA" to "TDO".
		Architecture	Updated text in Ripple Mode section.
			Added information to Global Set/Reset.
			Added information for Spread Spectrum Clocking
			Modified information for PLL/DLL Cascading. DLL to PLL is now supported.
			Modified AIL Block text and figure.
			Modified Figure 2-20 DDR/Shift Register Block.
			Added Information to Hot Socketing.
			Added new information for I/O Architecture Rules.
			Added information to SERDES Power Supply Sequencing Requirements.
		DC and Switching Characteristics	Added footnote to Hot Socketing Specifications table.
			Modified Initialization and Standby Supply Current table.
			Modified GSR Timing table.
			Modified sysCLOCK DLL Timing table to include $I_{DUTY.}$
			Deleted Readback Timing information from sysCONFIG Port Timing table.
			Modified data in External Switching Characteristics table.
		Pin Information	Added information to the Signal Descriptions table for HDC/SI, LDCN/SCS.
			Added footnote to Signal Descriptions table.
			Modified Description for signal BUSYN/RCLK/SCK.
			Modified data in Pin Information Summary and device-specific Pinout Information tables.